

L Number	Hits	Search		Time stamp
1	2	"5408053" .pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/15 15:55
2	0	transmission with diferent with dielectric	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/15 15:56
3	0	diferent with dielectric with constant same substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/15 15:56
4	673	dielectric with constant same substrate with transmission	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/15 15:58
5	673	dielectric with constant same substrate with transmission	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/15 15:58
6	469	dielectric with constant same substrate with transmission	USPAT	2003/02/15 16:01
7	22	dielectric with different with constant same substrate with transmission	USPAT	2003/02/15 16:01
54	1758	174/262	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/15 17:55
55	809	174/263	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/15 17:55
56	669	174/264	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/15 17:55
57	651	257/759	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/15 17:57
58	409	257/798	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/15 17:57
59	9	257/798 and transmission with lines	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/15 17:57
60	160	(174/262 174/263 174/264 257/759) and transmission with lines	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/15 17:58
-	2	6392164.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/13 15:02

-	7	("5039" "5408053" "5450290" "545936" "5473120" "5734560" "5835357").PN.	PAT	2003/02/11 14:26
-	3	("5120384" "5245136" "5262595").PN.	USPAT	2003/02/11 15:13
-	2094	(257/758).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/11 15:13
-	378	((257/758).CCLS.) and (radius diameter)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/11 15:14
-	280	((257/758).CCLS.) and (radius diameter)	USPAT	2003/02/11 15:23
-	9	("5386339" "5402003" "5521332" "5798563" "5880925" "6222262" "6292351" "6353189" "6370010").PN.	USPAT	2003/02/11 15:15
-	4	("5195053" "5219639" "5512514" "5869901").PN.	USPAT	2003/02/11 15:18
-	0	1993JP-0206678.ap,prai.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/11 15:24
-	2	JP-05206678-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/11 15:25
-	1	1993-291906.NRAN.	DERWENT	2003/02/11 15:24
-	473	(MULTILAYER or INTERCONNECTION with BOARD)same (ratio diameter radius) and 257/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/11 16:11
-	70	((MULTILAYER or INTERCONNECTION) with BOARD)same (ratio diameter radius) and 257/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/11 15:33
-	1285	((MULTILAYER or INTERCONNECTION) with BOARD)same (ratio diameter radius)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/11 15:33
-	630	((MULTILAYER or INTERCONNECTION) with BOARD)same (ratio diameter radius)	USPAT	2003/02/11 15:36
-	1677	((MULTILAYER or INTERCONNECTION) with BOARD)and (ratio diameter radius)with (through adj holes holes or vias)	USPAT	2003/02/11 15:55
-	11	("2869040" "4295184" "4663840" "4851614" "4970624" "5189261" "5191174" "5280414" "5359767" "5363280" "5414223").PN.	USPAT	2003/02/11 15:46
-	8	5736679.URPN.	USPAT	2003/02/11 15:46
-	1289	((MULTILAYER or INTERCONNECTION) with BOARD)and (ratio diameter radius)with (through adj holes holes or vias)) not ((MULTILAYER or INTERCONNECTION) with BOARD)same (ratio diameter radius))	USPAT	2003/02/11 16:00
-	924	((MULTILAYER or INTERCONNECTION) with BOARD)and (ratio diameter radius)with (through adj holes holes or vias)) not ((MULTILAYER or INTERCONNECTION) with BOARD)same (ratio diameter radius))) and (insulating dielectric)	USPAT	2003/02/11 16:01

-	781	((((MULTILAYER or INTERCONNECTION) with BOARD) and (ratio diameter radius) with (through adj holes holes or vias)) not ((MULTILAYER or INTERCONNECTION) with BOARD) same (ratio diameter radius))) and (ground power)	USPAT	2003/02/11 16:09
-	9	("3739469" "4494083" "4498122" "4543715" "5381306" "5623160" "5825084" "6137064" "6181551").PN.	USPAT	2003/02/11 16:03
-	34	4494083.URPN.	USPAT	2003/02/11 16:07
-	3	5644276.URPN.	USPAT	2003/02/11 16:09
-	14786	impedance same (diameter or radius ratio) and (ground power)	USPAT	2003/02/11 16:11
-	0	(MULTILAYER or INTERCONNECTION with BOARD) and 25.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/11 16:11
-	2717	(impedance same (diameter or radius ratio) and (ground power)) and (board PCB)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/11 16:12
-	177	((impedance same (diameter or radius ratio) and (ground power)) and (board PCB)) and multilayer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/11 16:20
-	0	(174/262.000).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/11 16:20
-	974	(174/262).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/11 16:21
-	442	((174/262).CCLS.) and (ground power)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/11 16:23
-	541	(439/876).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/13 17:39
-	3508	transmission with lines same substrate and impedance	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/13 15:07
-	0	(transmission with lines same substrate and impedance) and 174.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/13 15:03
-	0	174.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/13 15:04
-	1	("0000174").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/13 15:05

-	265	(174/264).CCLS.	PAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/13 15:06
-	0	174.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/13 15:05
-	0	257.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/13 15:05
-	0	257.ccls	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/13 15:05
-	6	(transmission with lines same substrate and impedance) and ((174/264).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/13 15:07
-	17	transmission with lines and ((174/264).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/13 15:09
-	11	(transmission with lines and ((174/264).CCLS.)) not ((transmission with lines same substrate and impedance) and ((174/264).CCLS.))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/13 15:09
-	5	("4494083" "4673904" "5012047" "5499005" "5644276").PN.	USPAT	2003/02/13 15:08
-	976	(174/262).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/13 15:09
-	61	transmission with lines and ((174/262).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/13 15:10
-	55	(transmission with lines and ((174/262).CCLS.)) not (transmission with lines and ((174/264).CCLS.))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/13 15:13
-	4355	transmission and lines and substrate	EPO; JPO; DERWENT; IBM_TDB	2003/02/13 15:15
-	881	(transmission and lines and substrate) and ground	EPO; JPO; DERWENT; IBM_TDB	2003/02/13 15:13
-	15	((transmission and lines and substrate) and ground) and diameter	EPO; JPO; DERWENT; IBM_TDB	2003/02/13 15:14
-	102	(transmission and lines and substrate) and diameter	EPO; JPO; DERWENT; IBM_TDB	2003/02/13 15:15
-	111925	transmission with lines	EPO; JPO; DERWENT; IBM_TDB	2003/02/13 15:15
-	1409	(transmission with lines) and diameter	EPO; JPO; DERWENT; IBM_TDB	2003/02/13 15:16

-	218	((transmission with lines) and diameter) and (insulating dielectric)	JPO; DERWENT; IBM_TDB	2003/02/13 15:16
-	34	4494083.URPN.	USPAT	2003/02/13 15:25
-	6	("2422160" "2938175" "4494083" "4816791" "5093640" "5994983").PN.	USPAT	2003/02/13 15:28
-	7	("4276558" "4626805" "5057798" "5229727" "5424693" "5428327" "5832598").PN.	USPAT	2003/02/13 15:34
-	3	5994983.URPN.	USPAT	2003/02/13 15:34
-	1	1993JP-0203378.ap,prai.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/15 10:39
-	1	JP-05203378-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/15 10:38
-	0	1992JP-013278.ap,prai.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/15 10:39
-	1	1992JP-0013278.ap,prai.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/15 11:02
-	1	1993-291906.NRAN.	DERWENT	2003/02/15 10:40
-	2	"6392164" .pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/15 15:05